

SPECIFICATION AND PERFORMANCE

Series	115U series	File	115U_Spec_2	Date	2021/1/27
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Scope:

This specification covers the requirements for product performance, test methods and quality assurance provisions of below:

P/N	DESCRIPTION
115U-A000	6P Nano SIM Socket, Push-Pull Type, 1.3H, 10u" Gold Plating

Performance and Descriptions:

The product is designed to meet the electrical, mechanical and environmental performance requirements specification. Unless otherwise specified, all tests are performed at ambient environmental conditions.

RoHS:

All material in according with the RoHS environment related substances list controlled.

MATERIALS

NO.	PART NAME	DESCRIPTION
1	INSULATOR	LCP UL94V-0, Black
2	CONTACT	Phosphor Bronze, contact area gold plating, solder tails gold flash, all under plating 50u" nickel.
3	SHELL	Stainless Steel, solder pad gold plating, under 30u" nickel plating over all

RATING

Rated Voltage	30V AC
Rated Current	1A Max. per pin
Operating Temperature	-40°C to +85°C
Storage Temperature	-40°C to +85°C
Durability	5000 cycles

ELECTRICAL

Item	Requirement	Test Condition
Contact Resistance	Initial: 100 mΩ Max. After test: 40 mΩ Max change.	Measured between plug solder tails and receptacle solder tails. (EIA-364-23)
Insulation Resistance	Initial: 1000 MΩ Min. At 100V DC	Test between center contact and outer shell of unmated samples of one minute. (EIA-364-21)

Dielectric Withstanding Voltage	500V AC(RMS) for one minute	Test between center contact and outer shell of one minute. (EIA-364-20)
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MECHANICAL

Item	Requirement	Test Condition
Durability	1. Contact Resistance: 40mΩ (Max.) change. 2. No damage.	Mate connectors up to 5000 cycles at a maximum rate of 400 to 600 cycles per hour prior to environmental test. (EIA-364-09)
Vibration	Finish 1. No electrical discontinuity more than 1μs. 2. No damage. 3. Contact Resistance: 40mΩ (Max.) change.	Mate card and subjected to the following vibration conditions, for a period of 2 hours in each of 3 mutually perpendicular axes, with passing DC 1mA during the test. Amplitude: 1.52mm P-P or 19.6m/s ² {2G} Frequency: 10-55-10Hz Shall be traversed in 1 minute. (EIA-364-28)
Mechanical Shock	Finish 1. No electrical discontinuity more than 1μs. 2. No damage. 3. Contact Resistance: 40mΩ (Max.) change.	Mate card and subjected to the following shock conditions. 3 mutually perpendicular axis, passing DC 1mA current during the test. (Total of 18 shocks) Test pulse: Half Sine Peak value: 490m/s ² {50G} Duration: 11ms (EIA-364-27)

ENVIRONMENTAL

Item	Requirement	Test Condition
High Temperature Life	1. Contact Resistance: 40mΩ (Max.) change. 2. Insulation Resistance: 100MΩ (Min.)	Temperature: 85±2°C Test time: 48 hours (JIS C0025)
Cold Resistance	1. Contact Resistance: 40mΩ (Max.) change. 2. Insulation Resistance: 100MΩ (Min.)	Temperature: -30±2°C Test time: 48 hours (EIA-364-31A)
Humidity	1. Contact Resistance: 40mΩ (Max.) change. 2. Insulation Resistance: 100MΩ (Min.)	There shall be no any excessive corrosion on the every part of connector. Temperature: 40±2°C Humidity: 90~95%RH Test time: 120 hours (EIA-364-31A)
Salt Spray	Finish	5±1% salt solutions, at 35±2°

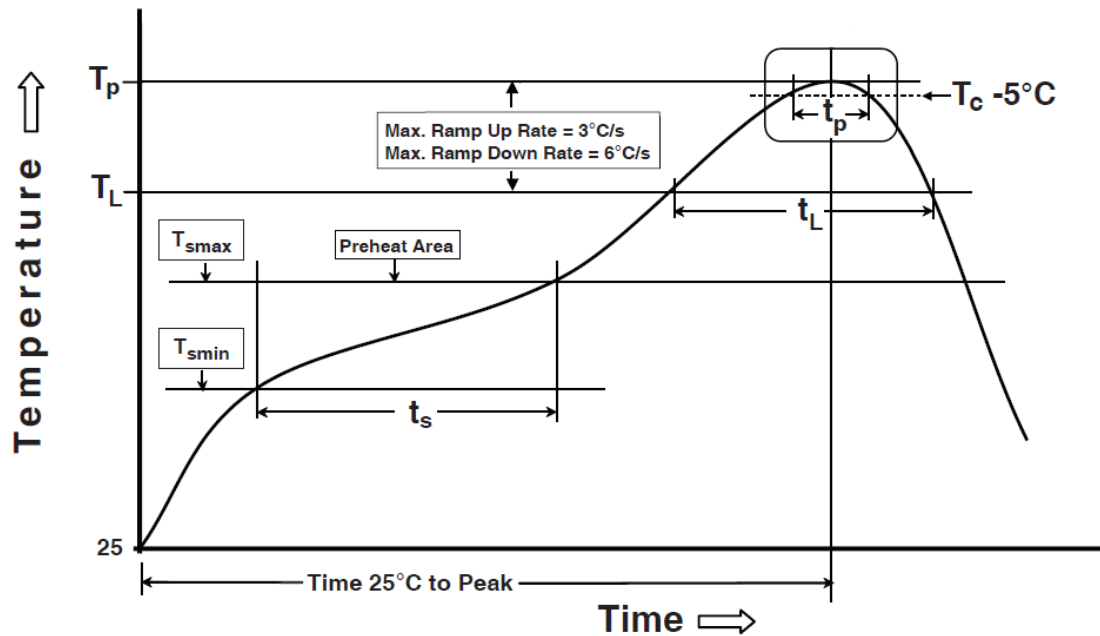


	1. Contact Resistance: 40mΩ (Max.) change. 2. No damage	duration 24 hours. Connectors detached (EIA-364-26A)
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SOLDER ABILITY

Item	Requirement	Test Condition
Solder-ability	95% of immersed area must show no voids, pin holes.	The termination should be 95% covered with new continuous solder coating. Solder temperature: 245±5°C Test time: 3±0.5 seconds (EIA-364-71)
Resistance to Soldering Heat	No melting, cracks or functional damage allowed.	When exposed to the following re-flow soldering condition, there shall be no any excessive thermal damage on the every part of connector.

Reflow Profile



Preheating temperature: 150 ~ 200°C, 60~120 seconds

Liquidus temperature (TL): 217°C, 60~150 seconds

Peak temperature: 260°C

Time within 5 °C of peak temperature (Tc): 255°C, 30seconds

Test Sequence:

Test Item	Test Group								
	A	B	C	D	E	F	G	H	I
Contact Resistance	1,4	1,3	1,3	1,3	1,4	1,4		1,3	
Insulation Resistance					2,5	2,5			
Dielectric Withstanding Voltage	2								
Durability	3								
Vibration		2							
Mechanical Shock			2						
High temperature				2					
Cold Resistance					3				
Humidity						3		3	
Solder ability							1		
Salt spray								2	
Resistance to Soldering Heat									1
Sample Quantity	4	4	4	4	4	4	4	4	4